Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S23	25	361/762 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S22	46	361/761 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S20	7	361/751 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S19	4	361/750 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S17	20	361/748 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S16	1	361/745 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S15	4	361/743 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S4	56	(solder adj1 mask) and (trench or recess or cavity) and MCM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
L8	27	361/762 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59

L7	47	361/761 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
L6	7	361/751 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
L5	5	361/750 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
L4	26	361/748 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
L3	1	361/745 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
L2	4	361/743 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
L1	82	(solder adj1 mask) and (trench or recess or cavity) and MCM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S31	41	174/52.2 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S30	55	174/262 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S29	22	174/263 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00

5/16/2006 9:01:37 AM Page 2 C:\Documents and Settings\dlevi\My Documents\EAST\workspaces\10623243 Overmolded MCM with increased surface mount capability

S28	48	174/250 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S27	79	174/260 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S25	12	361/736 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S24	45	361/764 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
L15	47	174/52.2 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
L14	63	174/262 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
L13	24	174/263 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
L12	52	174/250 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
L11	93	174/260 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
L10	13	361/736 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00

5/16/2006 9:01:37 AM
C:\Documents and Settings\dlevi\My Documents\EAST\workspaces\10623243 Overmolded MCM with increased surface mount capability

L9	47	361/764 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
----	----	--	---	----	-----	------------------

Page 4 5/16/2006 9:01:37 AM